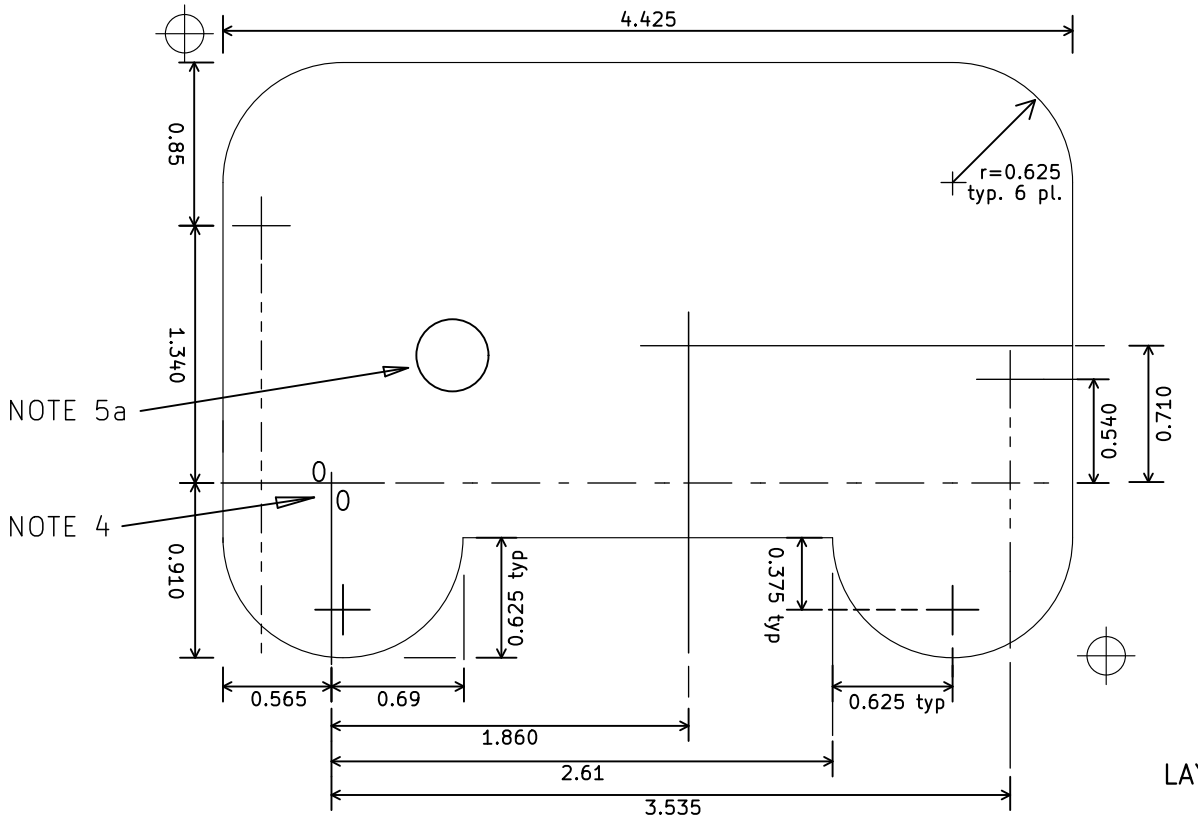
Be sure this is the latest version!

DATE	BY	REVISIONS	ISS.
2/26/14	PR	Initial release	T1
3/29/14	PR	C19: Fix reference text. S1-S7: Fix pin map. U4: Move pin 1 to 3V rail. C18: Place next to U4. DS1: Fix 24 & 26 reversed. D4/D5: fix interference. R16: Chg. 120 was 10K. ADD: Logo, radius corners. U4: Fix footprint. ADD: Batt. light [DS2], & layer stack up drawing. MISC: Fix drill hole sizes.	P1



NOTES:

1: DESCRIPTION:

.062" (nominal) Etched Circuit board, 2 side 1 oz (finished) Cu, for hybrid SMT/through lead. Minimum 8/8 SMT design rules. Not for lead free assembly.

2: MATERIAL & FINISH:

Refer to 00-PCB-README file for solder mask & silkscreen colors and quantities.

3. Dimensions:

Finish dimensions per drawing. +/- .005" on decimals, +/- .003" on holes, 1/64" on fractions, unless noted. Undimensioned holes to be positioned per artwork.

4. Co-ordinate System:

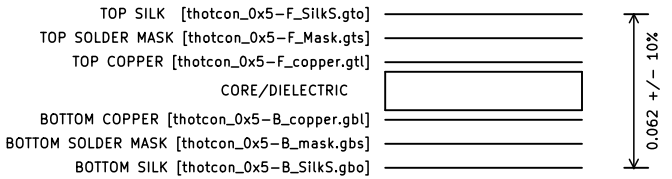
Drill file and SMT centroid 0, 0 origin (reference point) located per drawing.

5. ASSEMBLY:

a. DS2: LED mounts "face down" on SMD side. Verify presence and size of lens hole prior to assembly.
b. Manufacturer & RoHS labels on LC display DS1 must be removed prior to assembly.
b. Orient battery holders per legend. Refer to 00-ASM-README file.

LAYER STACK UP DETAIL

SMD COMPONENT Side



THROUGH-HOLE COMPONENT Side

SEE ALSO thotcon_0x5-F_Paste.gtp (top paste), thotcon_0x5-B_Paste.gbp (bottom paste)

LICENSE: CC-BY-SA-3.0
Project Mgr: R. Ristich
Designed: Paul Reich
Drawn: Paul Reich
Workshop 88

BOARD, PC, THOTCON 0x5

File: thotcon_0x5.brd
Sheet:
Title: BOARD, PC, THOTKON 0X5

Size: A	*Date: 31 mar 2014*	*Rev: P1*
KiCad E.D.A.		Id: 1/1